



AEM Holdings Ltd.

Annual General Meeting Presentation to Shareholders

23 April 2025 | The SingPost Auditorium

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In this presentation, all \$ dollar amounts are in Singapore dollars unless otherwise specified.

Contents



Company and Strategy Overview



Technology Leadership



Financial Review



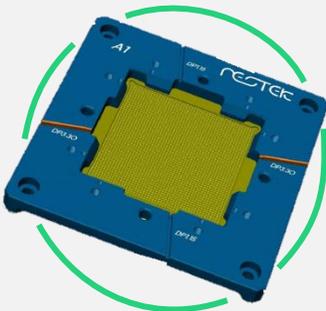
Leading Provider of Semiconductor Test Equipment and Manufacturing Services Serving Diversified End-Markets



Test & Automation Business, 63%* of revenue



Test Equipment



Consumables



Automation

* Includes Instrumentation Segment revenue

Contract Manufacturing Business, 37% revenue



PCB Assembly



Cable Assembly



System Assembly



FY2024 was a Transformative Year for AEM

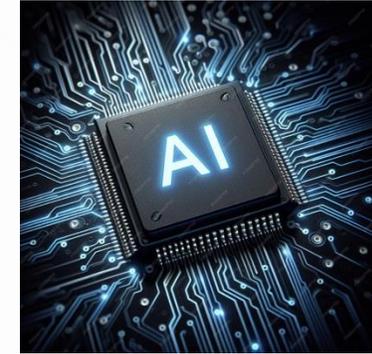
New product deployment in production to offset slow key customer recovery



Recognized as **Technology Leader in Thermal Management** for test



Launched industry **first high-power burn-in and system-level-test systems** for AI/HPC



Scaling with a major **new AI/HPC anchor customer** for production test

Technology Leadership, Production Volume

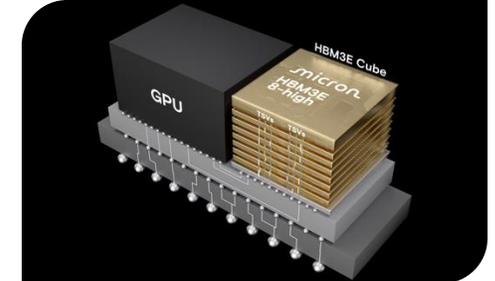
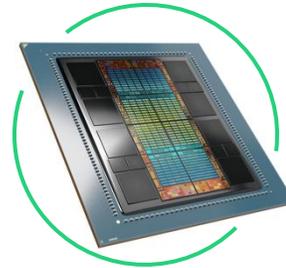


AI/HPC and Advanced Packaging Drive AEM's Growth in Test Segment

70%

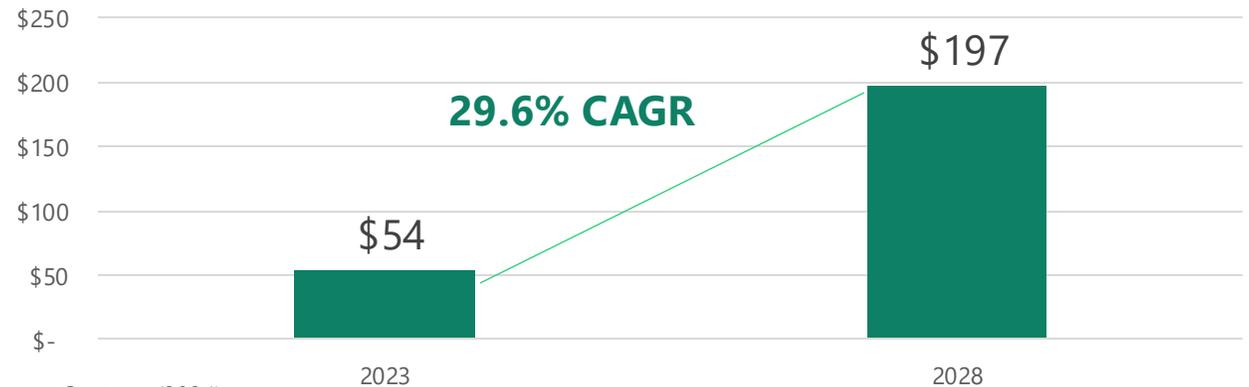
AEM Test New Customer Engagements was Driven by AI / HPC in 2024

Data Center AI Devices



Source: AMD, Intel, and Micron

AI Semiconductor Revenue (US\$, Billions)

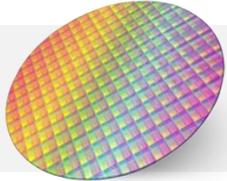


Source: Gartner (2024)

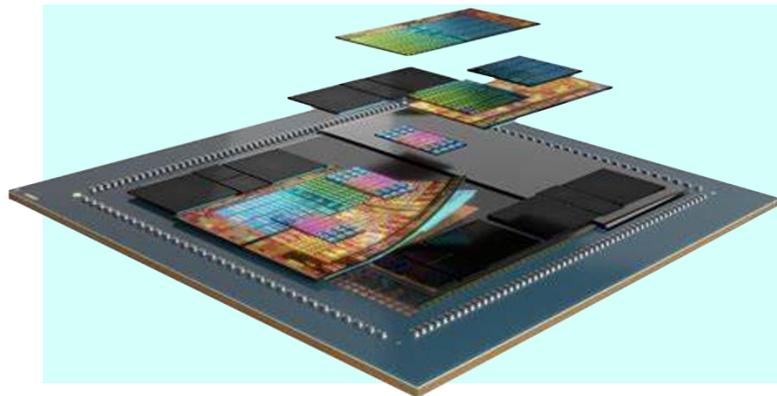


Increasing Chiplet Usage for Advanced Compute Applications

AEM test products are well-positioned to test increasingly complex chiplet packages



Wafer Probe



Chiplet Advanced Package Assembly*



Package Test Solutions

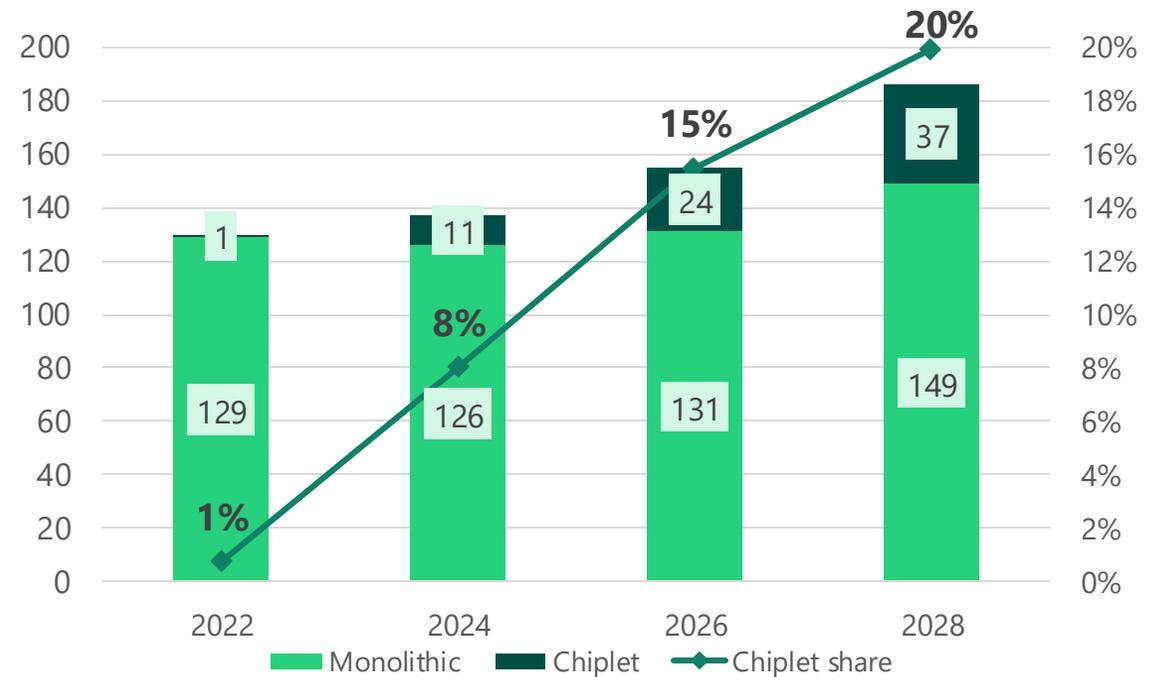
Burn-in

Final Test

System Level Test

*Source: AMD MI300 Package Example

Wafer Foundry Addressable Market (\$B)



*Source: CSM foundry model, ISM foundry model



Close Collaboration with Leading Customers to Enable Test 2.0

Chiplet Test Challenges



Higher Device Power



Thermal Management

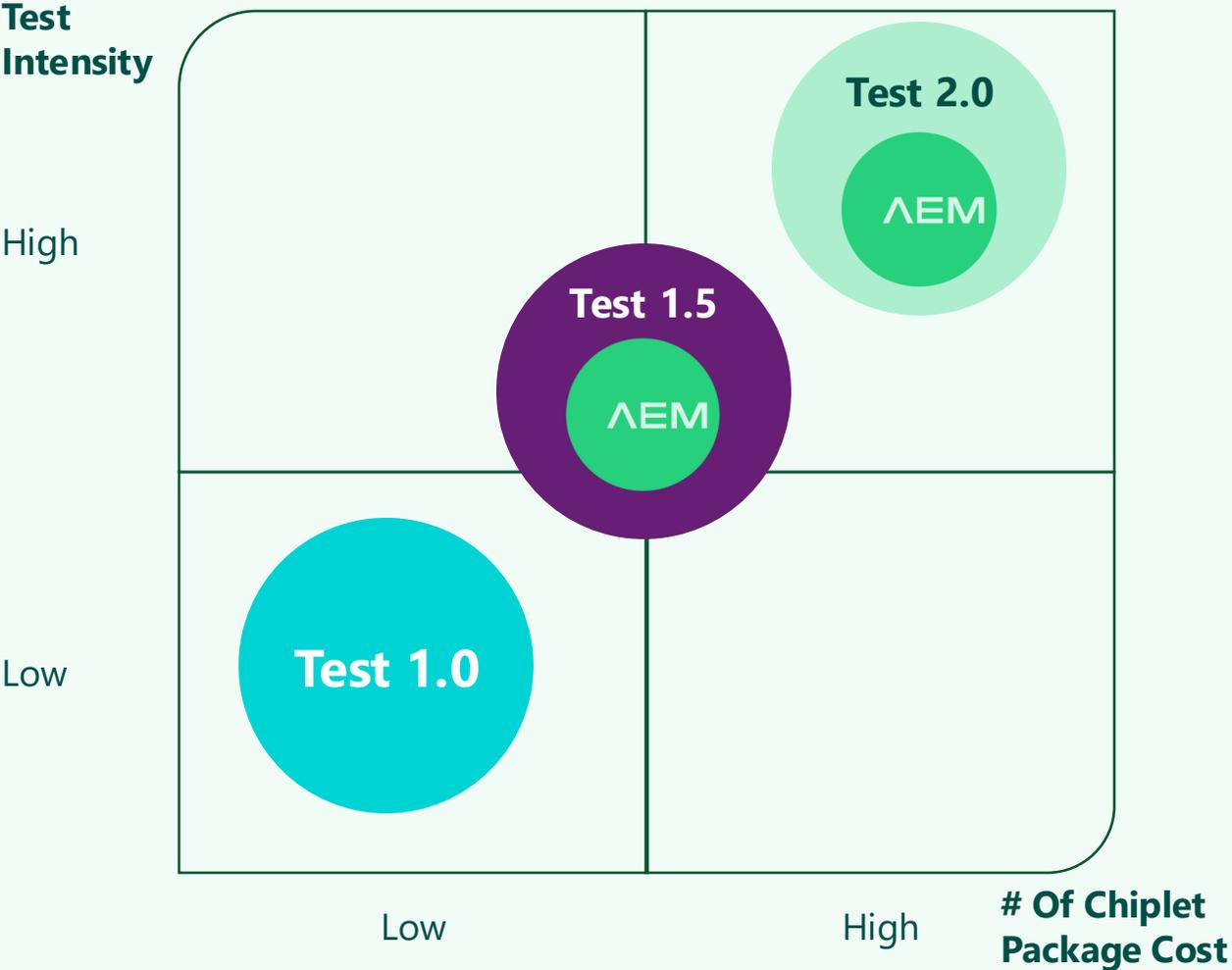


Increased Test Time



Complex Test Coverage

AEM Solutions





More Favorable "Razor / Blade" Business Model for AI Devices

Chiplet architecture accelerates time to market, increasing recurring business

Lifetime
"Blade" Revenue

> 2x

"Razor" Sales

Razor

System

Blade

Every 9-12 months

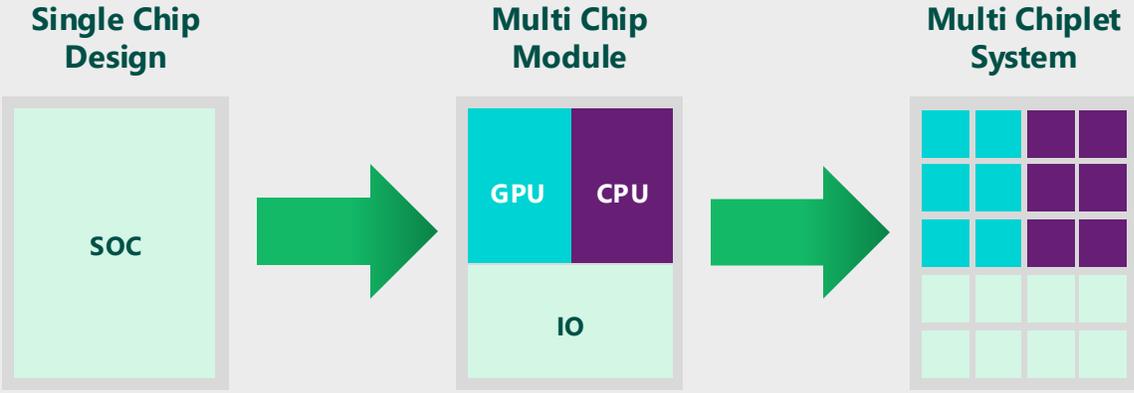
Device-specific Consumables

Test Slots Thermal Heads Test Sockets

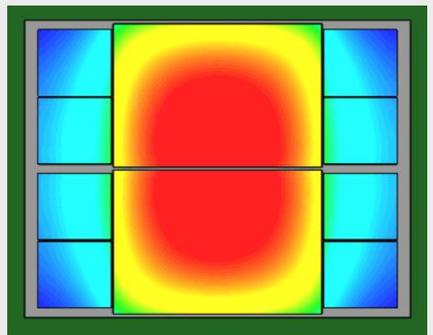
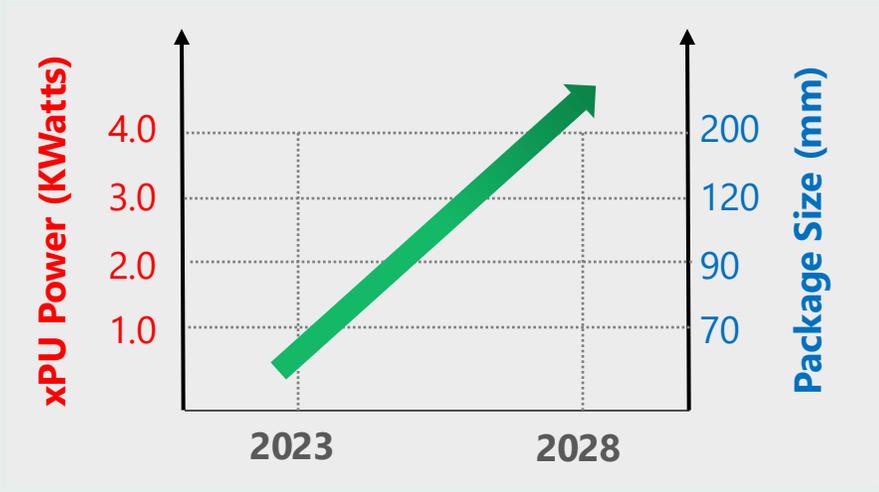


Advanced Packaging Driving The Need For New Test Technology

Many Chiplet Test Challenges



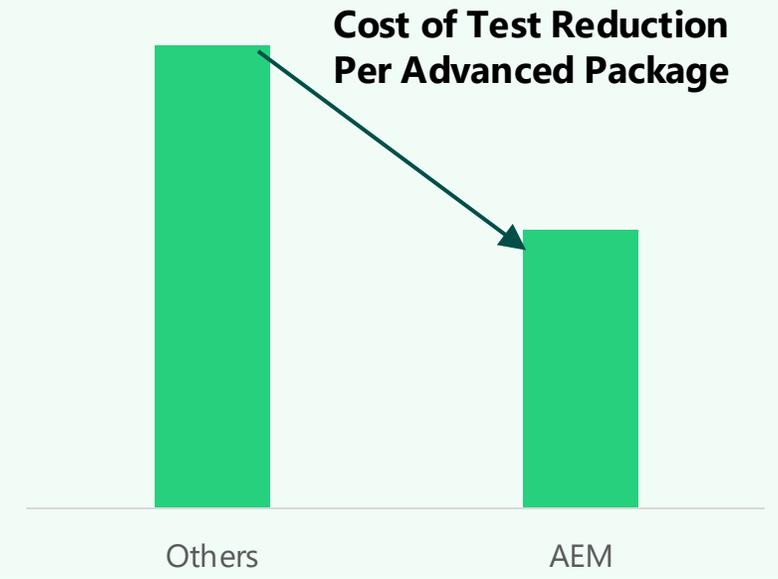
> 100 chiplets and IP zones per package



AEM Solution

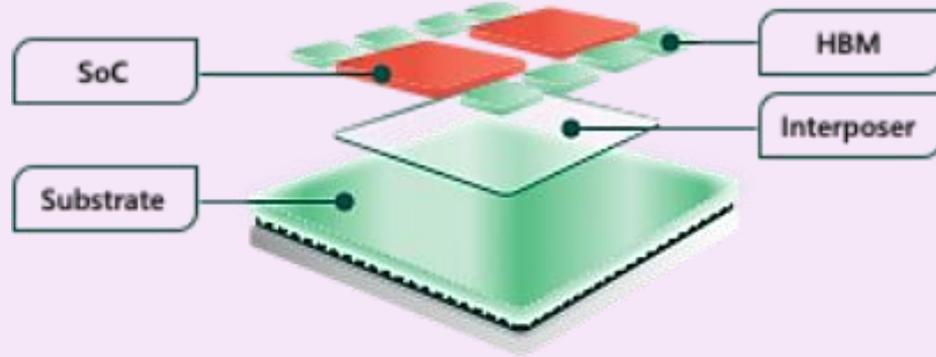


AEM's Patented Thermal Engine for Multi-zone Control

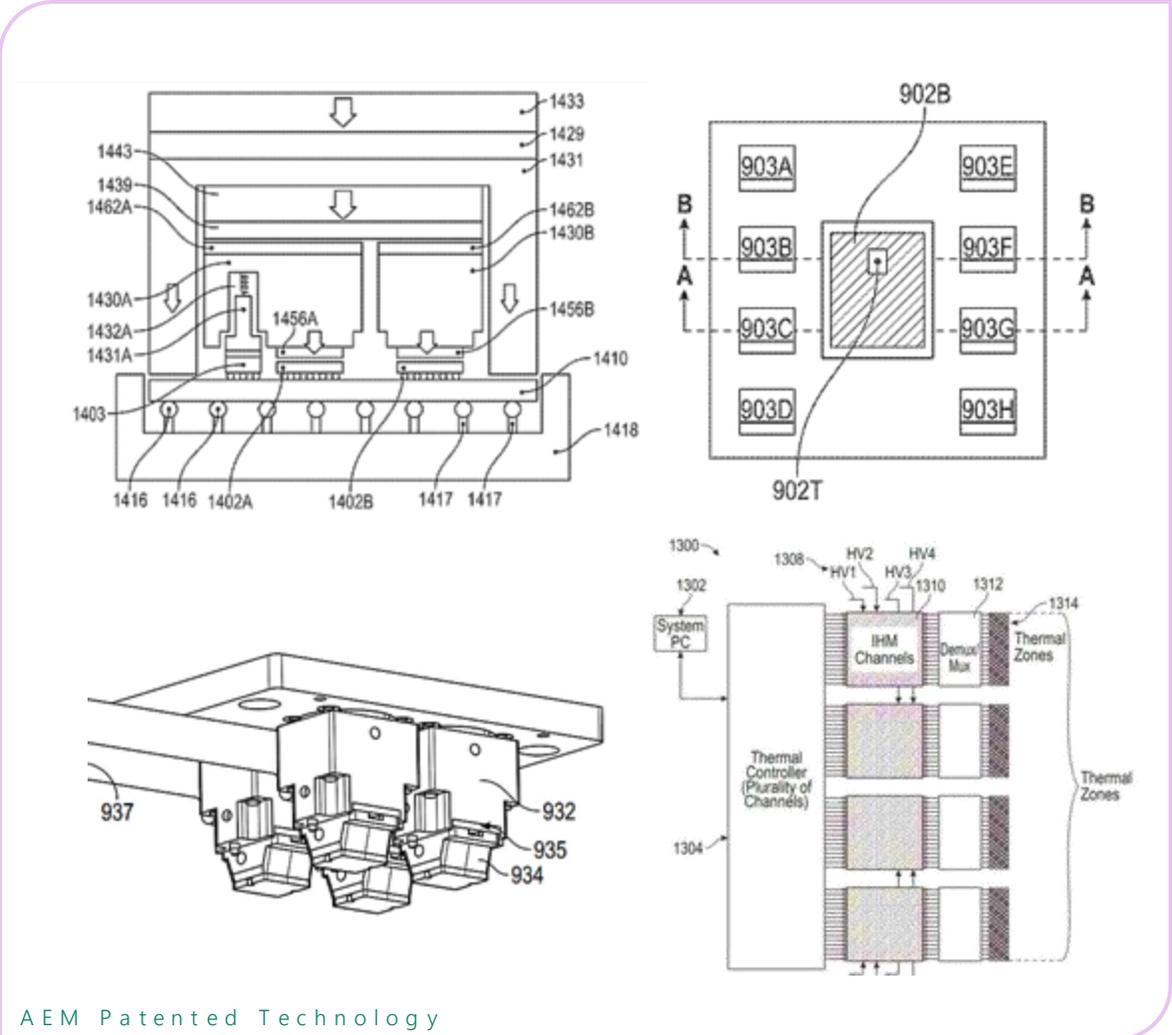




Pixelating Thermal Control to Support Chiplet Advanced Packages



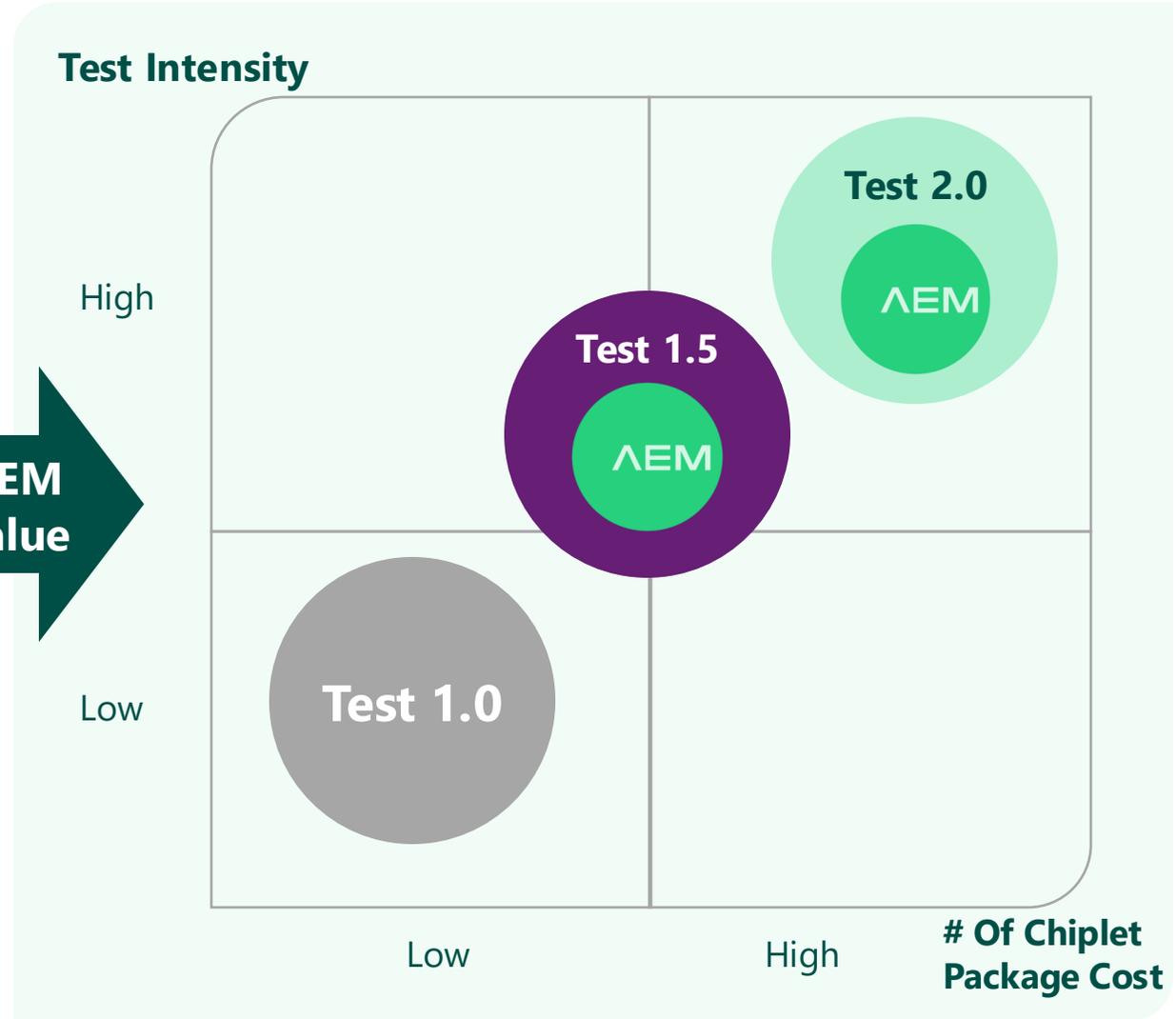
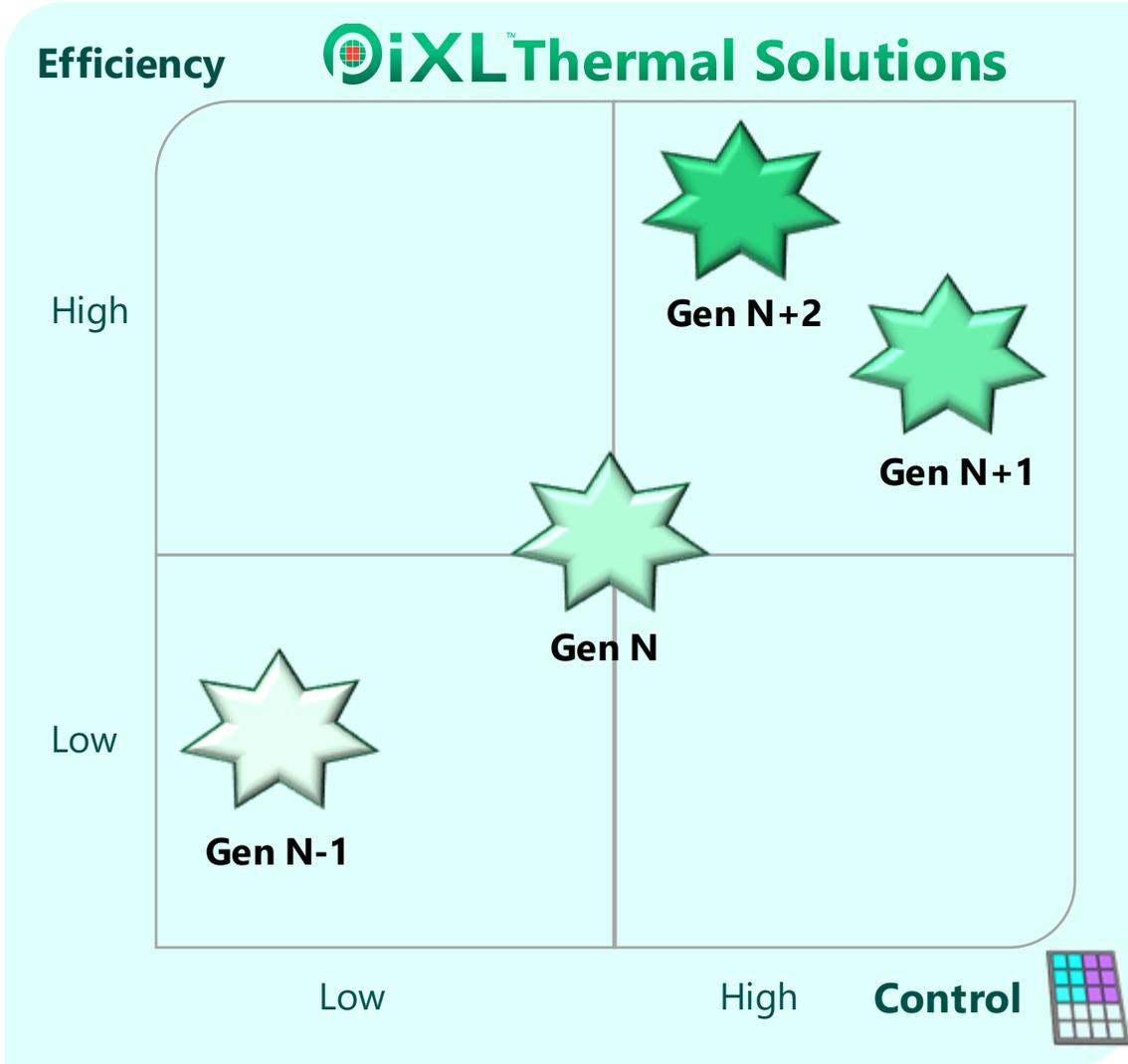
> 15 Patents Filed and Awarded on PiXL Thermal Technology



AEM Patented Technology



Multi-Generation Technology to Support Customers' Roadmap



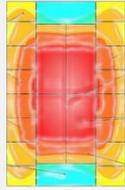


Customer Journey in Lab-to-Fab Deployment

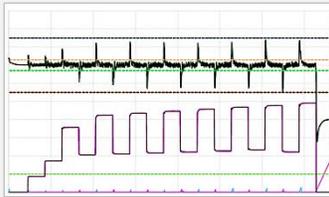
iXL™ Lab Thermal



Thermal Validation

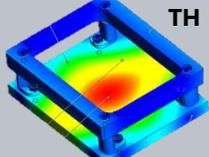
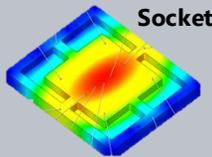
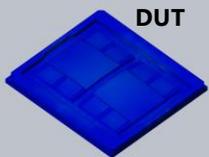


HPC Gradients



Transient Response

Mechanical Validation



AEM Patented Technology

Test 1.5



iXL™ Thermal Upgrades

- Generic Final Test Handlers
- Generic SLT Handlers
- Generic Burn-in Chambers

AEM Patented Technology

Test 2.0

iXL™ AEM Systems



Single Slot Engineering

AEM Patented Technology



High-throughput Production



What We Said in 2024 AGM

R&D Expenses **FY2023**
\$24.4M

Socket Technology
Wafer Probe Machine Vision
Thermal Software
Control Instrumentation
 Advanced Automation

9 Patents
Awarded in FY2023



Key Engagements

Memory
1 Large memory IDM for SLT

xPU
2 HPC / AI customers for AI Burn-In and HPC SLT

Systems / Hyperscalers
2 Application Processor customers for AP SLT



Committed R&D Investments Driving New Customer Diversification

FY2024
R&D Expenses **\$23.7M**

Socket Technology
 Wafer Probe Machine Vision
Thermal Software
Control Instrumentation
 Advanced Automation

15 Patents
 As of FY2024

Increase Engagements

Memory
 1 Large memory IDM for SLT, FT

xPU
 2 HPC / AI customers for AI Burn-In and HPC SLT

Systems / Hyperscalers
 2 Application Processor customers for SLT

Production

Early production SLT test for GDDRx in 2025

Customer 1
 Early production test in 2025

Customer 2
 Mid-volume production in 2025

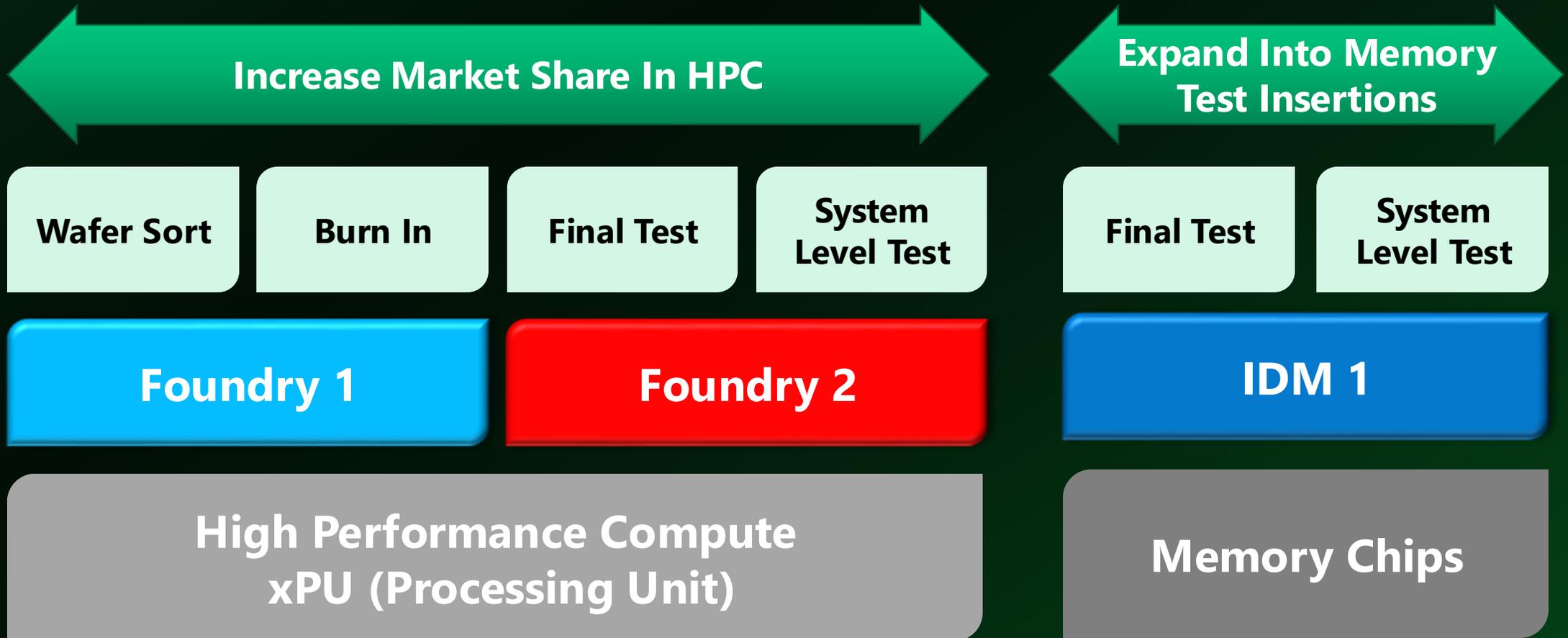


AEM's "Follow the Chiplet" Growth Strategy

Uniquely positioned inside two leading Foundry ecosystems and gaining traction in the Memory market



AEM's Patented Thermal Engine for Multi-zone Control





FY2024 Financial Highlights

Revenue at S\$380.4M and PBT (excluding exceptional items) at S\$19.8M



Revenue

S\$380.4M
-21% vs FY2023



PBT
(excluding exceptional items)

S\$19.8M
5.2% of Revenue

-48% vs FY2023
-2.8 pts vs FY2023

Gross Profit

S\$97.6M
25.7% of Revenue

-25% vs FY2023
-1.2pts vs FY2023

EPS (Diluted)

3.65 cents

vs (0.40 cents)
in FY2023

NAV per share

155 cents

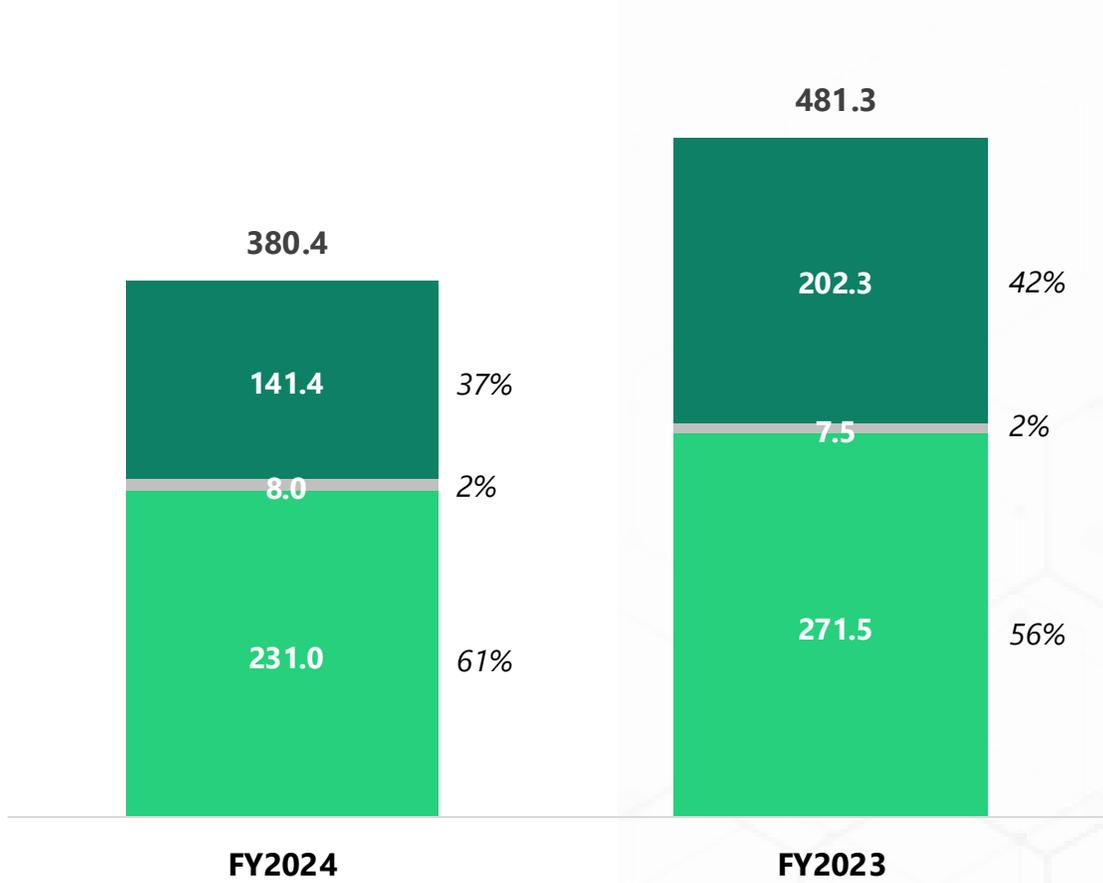
+2.6% vs Dec'23



Revenue Mix: FY2024 vs. FY2023

Test Cell Solutions revenue came in at S\$231M, contributing to 61% of revenue in FY2024

Total Revenue Mix (S\$M)



Test Cell Solutions Revenue Mix (S\$M)



■ Test Cell Solutions ■ Instrumentation ■ Contract Manufacturing

■ Test & Automation Equipment ■ Consumables ■ Services



Balance Sheet

A robust balance sheet with Debt / Equity at 0.2X

- **Receivables increased** due to customer shipments at end 4Q2024
- Total equity **S\$492.3 million**, up 3.8% from Dec'23
- NAV per share increased to **155 cents**, mainly driven by net profit for the period
- **Cash holdings used** to reduce financial liabilities and bank borrowings
- Stable capital structure, **with the debt-to-equity ratio of 0.2X**

As At

	Dec'24	Dec'23	Change
	S\$M	S\$M	%
Cash	43.8	101.8	(57.0)
Inventories	296.8	328.6	(9.7)
Trade and other receivables	142.7	58.8	142.7
Total Assets	673.2	707.5	(4.8)
Trade and other payables	54.0	74.1	(27.1)
Financial liabilities	94.4	126.4	(25.3)
Total Liabilities	180.9	233.1	(22.4)
Total Equity	492.3	474.4	3.8
In SG cents			
NAV per share	155	151	2.6
Debt / Equity	0.2X	0.3X	
No. of shares less treasury shares ('000)	313,022	308,902	



Charting the Future





Thank You!

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